



DOCUMENT CHANGE NOTICE (DCN)

DOCUMENT No. (DOC-REV-GP. ID)	TITLE	NEW REV.
D000243-A-D	Circuit Board Assembly, LED	B
D000244-A-D	Circuit Board Assembly, Photodiode	B

CHANGE DESCRIPTION (FROM/TO):

Zone A1:Notes; Remove Notes 1-5. Replace with Note 1.
From: Note 1. CLEAN ITEM 1 OR 2 THOROUGHLY BEFORE SOLDERING. DEFLUX BOARD.
 2. SOLDER ITEM 3 TO ITEM 1 OR 2 IN ORIENTATION SHOWN.
 3. SOLDER 3" SECTIONS OF ITEM 4 TO ITEM 1 OR 2.
 4. MAINTAIN PRESSURE ON ITEM 3 DURING SOLDERING TO REDUCE AMOUNT OF SOLDER UNDER PADS.
 5. USE PRESSURE ON ITEM 3 DURING SOLDERING TO MAINTAIN PARALLEL POSITION OF ITEM 3 TO EDGES OF CURCUIT BOARD, ITEM 1 OR 2.
To: Note 1. FABRICATION INSTRUCTIONS FOR THIS ASSEMBLY ARE DETAILED IN LIGO-E000388.

REASON FOR CHANGE: informational

ACTION: Incorporate change Attach DCN to drawing(s) Other action (specify):

DISPOSITION OF HARDWARE (IDENTIFY SERIAL NUMBERS)	DCN DISTRIBUTION (X=incl. docs)
<input checked="" type="checkbox"/> No hardware affected (record change only) <input type="checkbox"/> List S/Ns which comply already: <input type="checkbox"/> List S/Ns to be reworked or scrapped: <input type="checkbox"/> List S/Ns to be built with this change: <input type="checkbox"/> List S/Ns to be retested per this change: <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>	Barish Coles Coyne Lazzarini Lindquist Raab Sanders Shoemaker Stapfer Tyler Weiss Whitcomb Zydowicz Barton Jones Heefner X Romie Fritschel

SAFETY, COST, SCHEDULE, REQUIREMENTS IMPACT? No Yes (If yes, enter Change Request number)

APPROVALS:	DATE	OTHER APPROVALS (specify)	DATE
ORIGINATOR: J. Romie <i>J. Romie</i>	01-16-01		
TASK LEADER: J. Romie <i>J. Romie</i>	01-16-01		
GROUP LEADER: <i>D. Coyne</i>	3/28/01		
DCC RELEASE: <i>D. Moran</i>			



CALIFORNIA INSTITUTE OF TECHNOLOGY
 MASSACHUSETTS INSTITUTE OF TECHNOLOGY

DCN No. **E010013-00-D**

SHEET **1** OF **1**

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-
-
-
-

DCN DISTRIBUTION (X=incl. docs)

Coyne	Barish	Coles
Raab	Lazzarini	Lindquist
Stapfer	Sanders	Shoemaker
Whitcomb	Tyler	Weiss
	Zydowicz	
Barton		
Jones		
Heefner		
X Romie		
Fritschel		

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TASK LEADER: J. Romie <i>J. Romie</i>	01-16-01		
GROUP LEADER:			
DCC RELEASE: <i>J. Romie</i>	4-18-01		